

Abstract

A method of packaging a photonic component and a photonic component package are provided. The package comprises a package body a set of pins, wherein the orientation of the pins does not increase the footprint requirements of the package when the package is mounted onto a module. A semiconductor die is attached to and enclosed within the package. The die may be a MEMS and may include a movable mirror. An optical fiber is attached in a parallel orientation to a mounting surface of the module. The package is a low cost part with pins attached on a pinout side. An optional photonic inlet of the package is additionally coupled with one or more external photonic elements. The photonic inlet is positioned relative to a through hole to allow light to travel between the MEMS die and the external photonic element. The photonic inlet and one or more external photonic elements may be partially enclosed by a boot that provides increased mechanical stability when the package is coupled with a printed circuit board.